

# APPROVAL SHEET

# MULTILAYER CERAMIC ANTENNA

# **RFANT BROADBAND Series**

2.4 GHz ISM Band Working Frequency

# RFANT7635110A1T

\*Contents in this sheet are subject to change without prior notice.



# **Walsin Technology Corporation**

# **REVISION HISTORY**

Rev	P/N	Description	Date
V01	RFANT7635110A1T	First Version	2004-07-13
V06	RFANT7635110A1T	Increase Revision History as Page-2 Update the "±" Mark.	2004-12-08



#### **FEATURES**

- ☐ Surface Mounted Devices with a small dimension of 7.6 x 3.5 x 1.1 mm³ meet future miniaturization trend.
- 380MHz broad bandwidth design makes less influence, less frequency shifting due to outside environmental deviation.
- □ 70% small footprint compared to normal band design (140MHz).
- ☐ Embedded and LTCC (Low Temperature Co-fired Ceramic) technology is able to future integrate with system design as well as beautifying the housing of final product.
- ☐ High Stability in Temperature / Humidity Change
- □ Free Impedance Matching

#### **APPLICATIONS**

- □ Bluetooth
- □ Wireless LAN
- □ HormRF
- □ ISM band 2.4GHz wireless applications

#### **DESCRIPTION**

Walsin Technology Corporation develops a new ceramic embedded antenna specified for 2.4 GHz ISM Band application, as shown in below "CONSTRUCTION". Both of Wireless LAN IEEE 802.11b and Bluetooth<sup>TM</sup> typically located on this unlicensed frequency band which range covers from 2.4GHz to 2.4835GHz. To fulfil the friendly usage for antenna, this antenna has been designed to a typical 400MHz bandwidth through Walsin's advanced LTCC (Low Temperature Co-fired Ceramic) technology and superior product design via 3D EM Simulation Skill.

This antenna has a rectangular ceramic body with a tiny dimension of 7.6 x 3.5 x 1.1 mm<sup>3</sup> meet the future SMT automation and miniaturization requirements on modern portable devices.

#### CONSTRUCTION

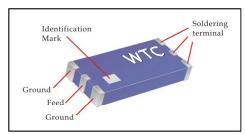


Fig 1. Outline of 2.4GHz Chip Antenna

#### **DIMENSIONS**

Figure		Dimension	Port definition
L	L	7.60 ± 0.30 mm	-
	W	3.50 ± 0.20 mm	-
$\uparrow$ G $\downarrow$ P <sub>1</sub>	Т	1.10 ± 0.10 mm	-
$W \vdash_{Fd} V \vdash_{P_3} V \vdash_$	Fd	0.50 ± 0.20 mm	Feed termination
W Fay	G	0.80 ± 0.20 mm	Ground termination
$ \stackrel{\bullet}{\longrightarrow} G \stackrel{\updownarrow}{\downarrow} \qquad \qquad$	O	0.50 ± 0.20 mm	
$\begin{array}{c c} \longrightarrow & \longleftarrow & C \\ & D \longrightarrow & \longleftarrow & \bot \end{array}$	D	0.50 ± 0.20 mm	
	P <sub>1</sub>	0.80 ± 0.20 mm	Solder termination
	P <sub>2</sub>	0.80 ± 0.20 mm	Solder termination
	P <sub>3</sub>	0.50 ± 0.10 mm	Solder termination

**MARKING:** Upon customer requested, max. 5-digit code is allowed.



# **SOLDER LAND PATTERN DESIGN**

Figure	Symbol	Dimension
<b>→</b>	L	8.10 ± 0.10 mm
Lp Ws	Lp	1.00 ± 0.10 mm
Lh Wf	Wp	1.20 ± 0.10 mm
↓ ↓ ↓ ↓ Lf	Lf	1.50 ± 0.10 mm
Tg 🖘	Wf	0.80 ± 0.10 mm
w g	Lg	1.50 ± 0.10 mm
Soldering Pad	Wg	1.50 ± 0.10 mm
Ground Pad connected to Ground Pad connected to 50Ω	Ws	0.40 ± 0.10 mm
Transmission Line	Lh	0.50 ± 0.10 mm

# **ELECTRICAL CHARACTERISTICS**

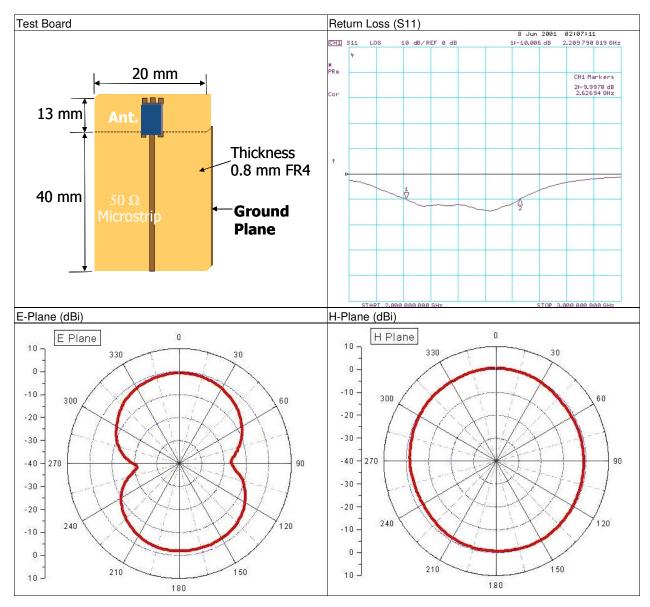
ltem	Specification	
Central frequency	2.450 GHz (Note-1)	
Bandwidth	380 MHz (Typical value)	
Gain	0 ~ 2 dBi	
VSWR	2 max.	
Polarization	Linear	
Azimuth Bandwith	Omni-directional	
Impedance	50Ω	
Rated Power (max.)	5 Watts	
Maximum Input Power	10 Watts for 5 minutes	
Operation Temperature	-40° C ~ +85° C	

Note-1. Central Frequency should be defined after customers' application approval.



#### **RADIATION PATTERN**

Radiation Pattern and Gain were dependent on measurement board design. Walsin's LTCC chip antenna is an electrically small antenna (size smaller than  $1/10\lambda$ ). The specification of RFANT7635110A1x series chip antenna was measured based on the PCB size and installation position as shown in the below figure



The typical tuning range of Walsin's chip antenna is about ±150MHz. The performance of embedded ceramic antenna is sensitive influenced by customer's ground area, PC board size, thickness, material, mechanical design and the material of housing for end product.

WTC engineers have significant expertise on embedded antenna designs and applications. We can work closely with you to ensure the requirements are met, and optimise the WTC's antenna performance when installing on your application.



# **RELIABILITY TEST**

# ■ Mechanical performance

Test item	Test item Test condition / Test method		
Solderability	Solder temp. : 235 ± 5°C	95% min. coverage of all	
	Immersion time: 2 ± 1 sec	metabolised area	
	Solder: SN63		
Resistance to soldering heat	Solder: Sn63	No mechanical damage.	
	Preheating temperature: 150 ± 10°C	Ceramic surface shall not be	
	Solder Temperature: 260 ± 5°C	exposed in the middle of the termination or on the terminated	
	Immersion time: 10 ± 1 sec	product edge by leaching.	
	Measurement to be made after keeping at room temp. for 24 $\pm$ 2 hrs.		
Dren toot	Height . 75 am	No machanical damage	
Drop test	Height: 75 cm	No mechanical damage.	
	Direction : 3 directions	Samples shall satisfy electrical specification after test	
	Times : 3 times for each direction.	oposinoanon anor tooti.	

# ■ Environmental characteristics

Test item	Test condition / Test method	Specification	
Humidity Resistance	Humidity:90% to 95% R.H.	No mechanical damage.	
	Tempertaure:40±2°C	Samples shall satisfy electrical	
	Time: 500±24 hours.	specification after test.	
	Measurement: After placing for 24 hours Minimum.		
Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.	
	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical	
	3. 30±3 minutes at +85°±3°C,	specification after test.	
	4. 10~15 minutes at room temperature,		
	Total 100 continuous cycles		
	Measurement after placing for 48±2 hrs min.		
High temperature	Temperature: 85°C±2°C	No mechanical damage.	
	Test duration: 24 hours	Samples shall satisfy electrical	
	Measurement must be taken after subjection to the above conditions, followed by exposure in room environment for 1 to 2 hours.	specification after test.	
Low temperature	Temperature: -40°C±3°C	No mechanical damage.	
	Test duration: 24 hours	Samples shall satisfy electrical	
	Measurement must be taken after subjection to the above conditions, followed by exposure in room environment for 1 to 2 hours.	specification after test.	



# **SOLDERING CONDITION**

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2

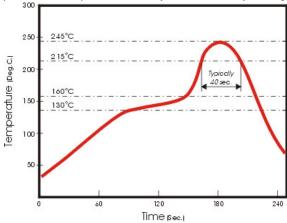
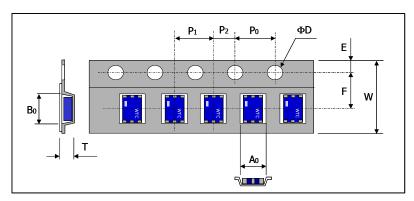


Fig 2. Infrared soldering profile

# **ORDERING CODE**

RF	ANT	763511	0	Α	1	- T
Walsin	Product	Dimension	Unit of	Application	Specification	Packing
RF	code	code	dimension	A: 2.4GHZ ISM	Code from 0 ~ 9	T: 7" Reeled
device	ANT :	Per 2 digits of	0 : 0.1 mm	Band	dependent on	G: 10" Reeled
	Antenna	Length, Width,	1 : 1.0 mm	B: GSM 900/1800	different electrical	B : Bulk
		Thickness :		Dual Band	specification	X : SFC product
		e.g. :		C : GSM 900		· ·
		763511 = Length		D: GSM 1800		
		76, Width 35,		E : GPS		
		Thickness 11		F:W-CDMA		
				G:PHS		

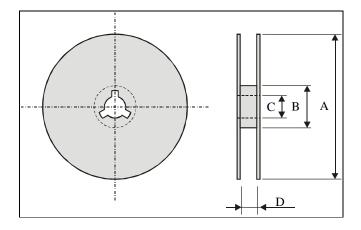
# PACKAGING: Plastic Tape specifications (unit :mm)



Index	Ao	Во	ΦD	Т	W
Dimension (mm)	3.86 ± 0.10	7.92 ± 0.10	1.55 ± 0.05	1.35 ± 0.10	16.0 ± 0.30
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	7.50 ± 0.10	4.00 ± 0.10	8.00 ± 0.10	2.00 ± 0.10



#### **Reel dimensions**



Index	Α	В	С	D
Dimension (mm)	Ф178	Ф60.0	Ф13.5	16.5±0.1

Typing Quantity: 1000 pieces per 7" reel

#### **CAUTION OF HANDLING**

#### **Limitation of Applications**

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

### Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
  - Products should be storage in the warehouse on the following conditions.

Temperature : -10 to +40°C

Humidity: 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.